

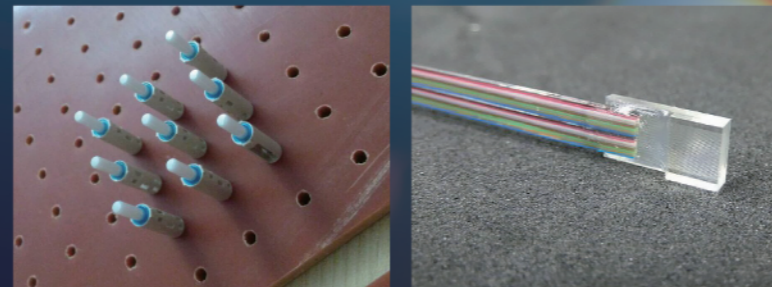
Photo-curing adhesive for optical fiber bundles fixation after assembly of optical communication device

Product Feature :

- * Colorless, easy to distinguish after curing
- * Low shrinkage <3%
- * Fast curing with light energy 1000mj/cm²

Product Model :

- * GN827 Series One-component UV adhesive
- * GN435 Series One-component UV adhesive



Optical fiber cold splicing module

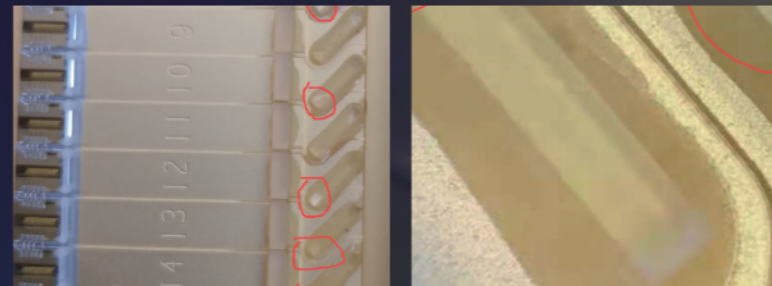
Photo-curing and cationic adhesive for glass lens encapsulation and metal substrate of laser modules

Product Feature :

- * Ultra-high powder content >80%, it can conform to the requirements of low shrinkage after curing
- * The formula of aerospace resin, it can withstand high temperature above 200°C
- * Fast curing with light energy 6000mj/cm²

Product Model :

- * JD422 Low viscosity series One-component cationic
- * JD451 Low shrinkage series One-component cationic

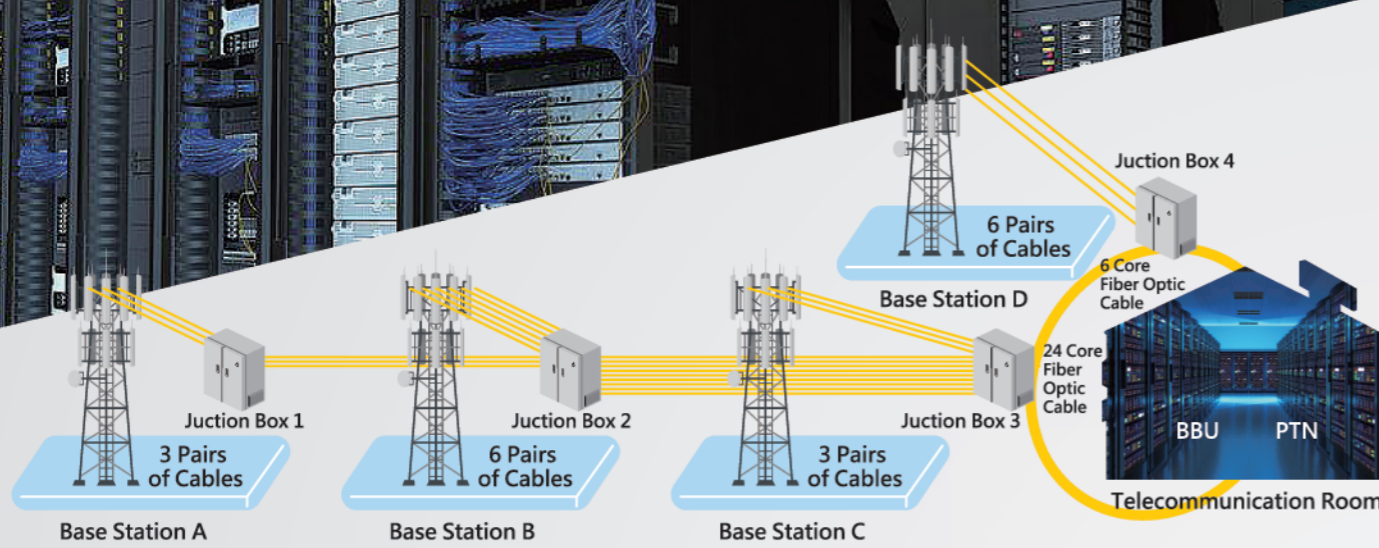


Everwide Chemical have invested many R&D engineers in the optical communication industry to be responsible for professional project R&D for different types of adhesive. Therefore, various product series have been derived to meet various special requirements of customers. If you have a special idea about the structure at the beginning of the design, you can connect with our R&D team in advance. We are dedicated to customizing products to meet your requirements, which is the characteristic of our market application operation.

www.everwide.com.tw

**Encapsulation Application Materials for
Optical Communication and
Laser Device Module Industry**





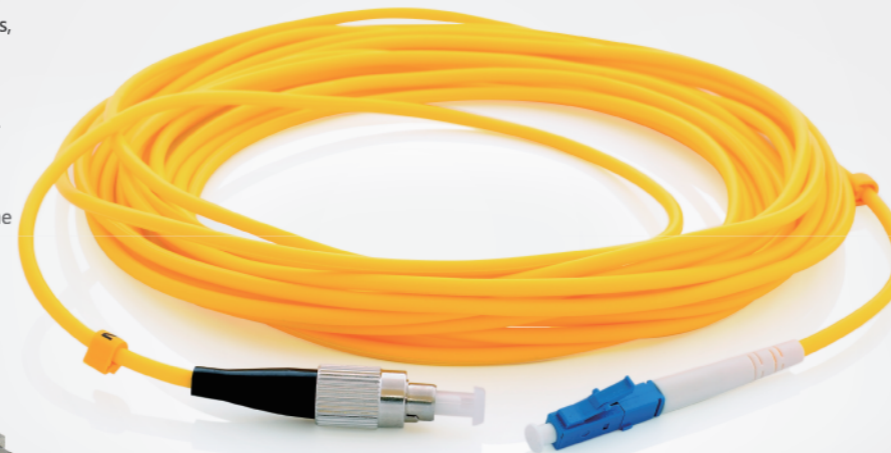
All products comply to the requirements of the optical communication industry environmental test : Telcordia GR-1221-CORE standard

1. Mechanical shock : shock level - 500G, duration - 1 ms.
2. Vibration test : frequency - 20 ~ 2,000 Hz, duration - 4 min per cycles and 4 cycles per axi.
3. Thermal shock test : every 30 min the temperature change to -40°C and 85°C, temperature conversion for 5 min, total 500 cycles.
4. Dry heat test : 85°C, humidity - < 40%RH, test duration : 2,000 hours.
5. 85°C high temperature and 85% RH high humidity test, test duration : 100,168,500,1,000,5000 hours.
6. -40°C low temperature test for 2,000 hours.

Application on optical communication module connector industry

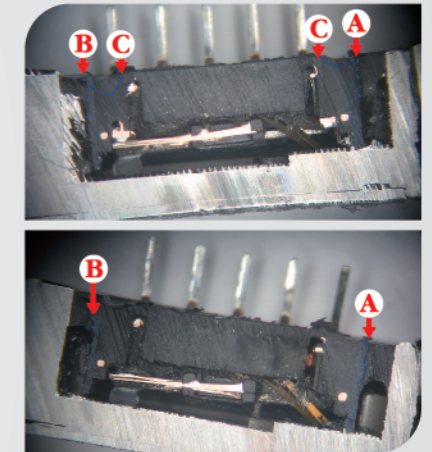
The application of this industry is very extensive, there are phototransducer, optical receivers, patch cords, multipliers, bidirectional connectors, DWDM and other products. We mainly supply this industry for the application of the fixed connection. The main features of products are :

- Anti-sag properties of the photo-curing adhesive and the light transmission will not be affected by low shrinkage.
- The optical components have good adhesion characteristics, and the refractive index conforms to the requirements of this industry.
- Comply with every detailed work requirements, and it also conform to the appropriate operating procedures in the industry.
- High temperature resistance, thermal cycling resistance, excellent aging resistance, two-component epoxy ratio 10:1 hypoallergenic environmentally friendly product that is not harm to hands.
- There are four types which are including, photo-curing adhesive, cationic epoxy, high-temperature resistance of one-component epoxy resin and two-component epoxy resin. The perfect packaging, stable quality, and physical properties are compared with the United States and Japan.



Fine chemical materials supplier need to have technical and professional analysis capabilities

For example, after confirming the potting material is fully cured, then taking the above environmental simulation test. The cross section analysis is performed, find out the colloid problem. After that do the fine-tuning of the formula, the developments of R&D capability shows that a qualified supplier in the optical communication industry.

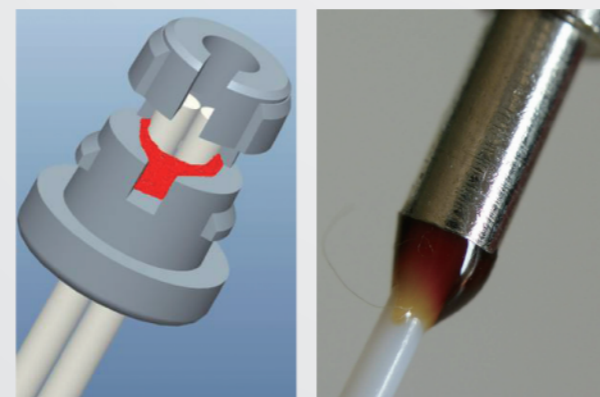


Industrial resin introduction : Based on the practical application of corresponding products

High crystallized glass fiber and fiber optic connector bonding---High temperature resistance wafer level sealing---Two-component epoxy resin

- Product Feature :**
- * Low temperature curing at 80°C*30min, 150°C*1min
 - * Low volume shrinkage 2.1%
 - * Low ionic volatilization
 - * Comply to reliability test, thermal cycle, thermal shock, high temperature and high humidity, high temperature heating test
 - * Low-volatile and low-irritant formula, no harm to hands, no allergies to skin

- Product Model :**
- * JB267 Low viscosity series Two-component epoxy
 - * JB271 Medium-high thixotropoc index, anti-sag series Two-component epoxy
 - * JB273 Low viscosity and black color series Two-component epoxy
 - * JB245 Low viscosity and low temperature curing series Two-component epoxy



WDM Multiplexer

Epoxy resin for optical fiber components in stainless steel module and ring-shape sealant

- Product Feature :**
- * Medium viscosity, easy and fast dispensing
 - * At 100°C * 30 min low temperature with fast curing properties

- Product Model :**
- * JD034 Series One-component epoxy
 - * JB271AB Series Two-component epoxy



GPON OLT BOSA



Epoxy resin for potting application in optical communication module

- Product Feature :**
- * The adhesive formula has toughened and anti-cracking performance
 - * Moderate working time, easy to defoam after potting

- Product Model :**
- * JC750 Series One-component epoxy
 - * JD140 Series Two-component epoxy



Sensor

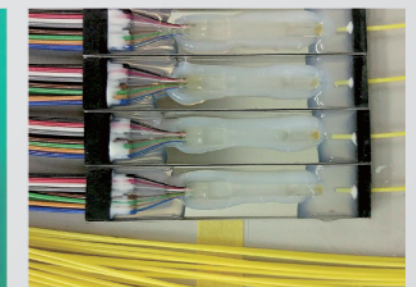
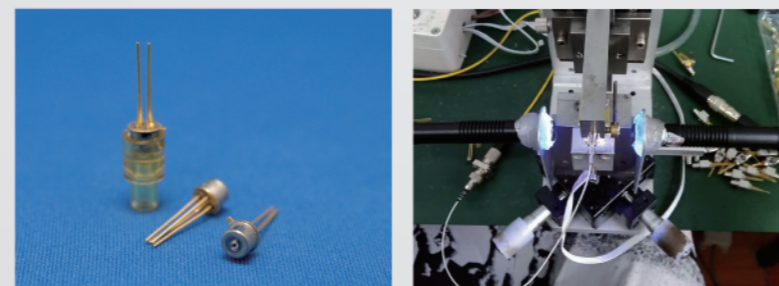


Photo-curing adhesive for fixation in optical fiber components

- Product Feature :**
- * A point of UV source can be fix within 3sec,1000~1500mj/cm²
 - * Low shrinkage 2.5%

- Product Model :**
- * JD474 Series One-component photo-curing adhesive
 - * JD167 Series One-component photo-curing adhesive

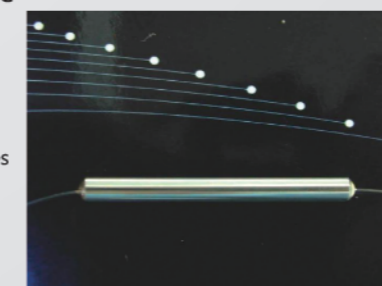


PON BOSA

Epoxy resin for optical signal filter both side encapsulation

- Product Feature :**
- * High viscosity, high thixotropic, non-flowable
 - * Low shrinkage <3%
 - * At 100°C * 30 min low temperature with fast curing properties

- Product Model :**
- * JB542 Series One-component epoxy



Wave filter

